

SOT1656-2

BGA1292, plastic, ball grid array; 1292 balls; 1 mm pitch; 37.5 mm x 37.5 mm x 3.17 mm body

1 May 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA1292
Package style descriptive code	BGA (ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	11-04-2019
Manufacturer package code	98ASA01433D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	37.5	-	mm
package width	-	37.5	-	mm
package height	-	3.17	-	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	1292	-	



2 Package outline

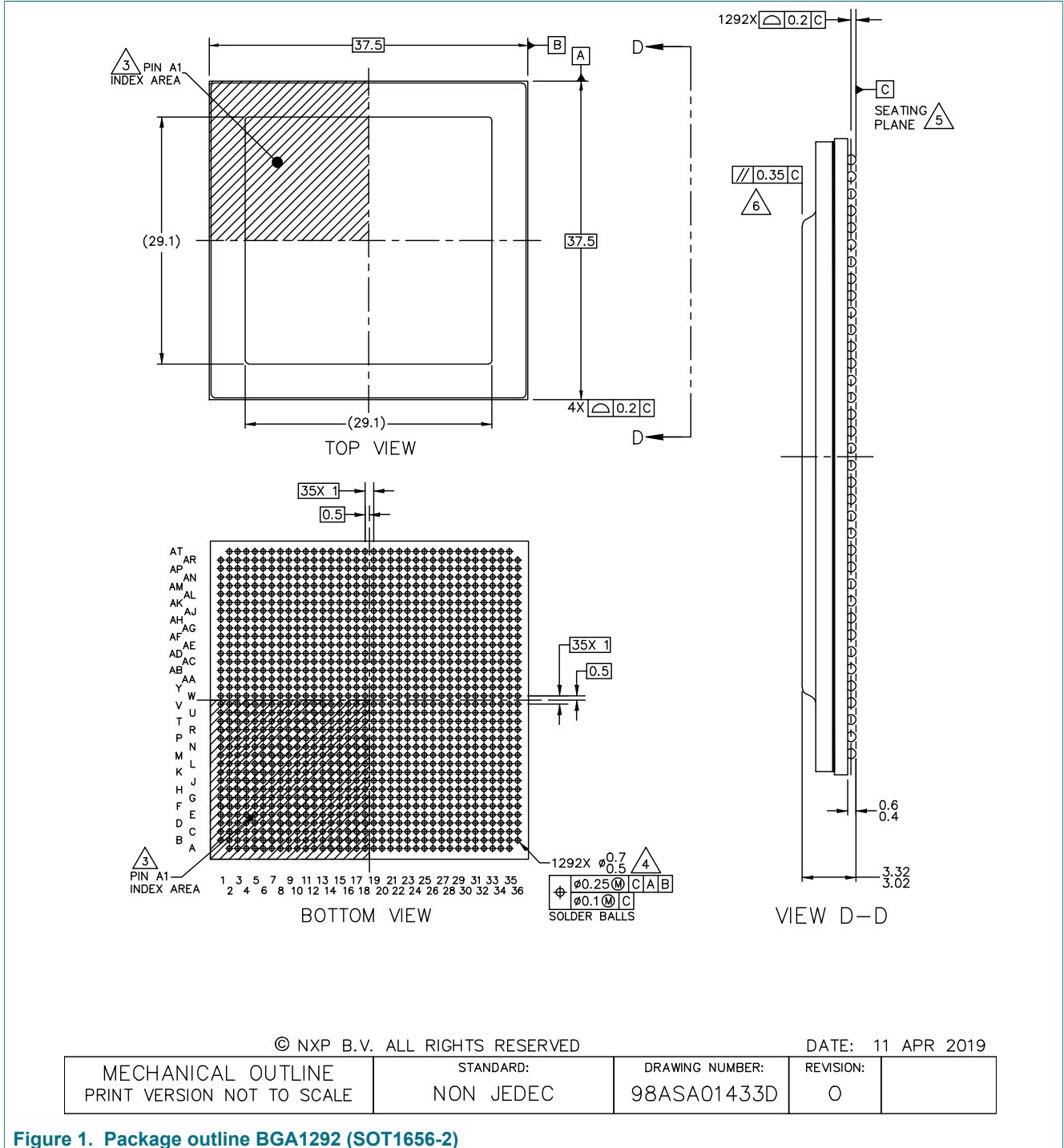


Figure 1. Package outline BGA1292 (SOT1656-2)

3 Soldering

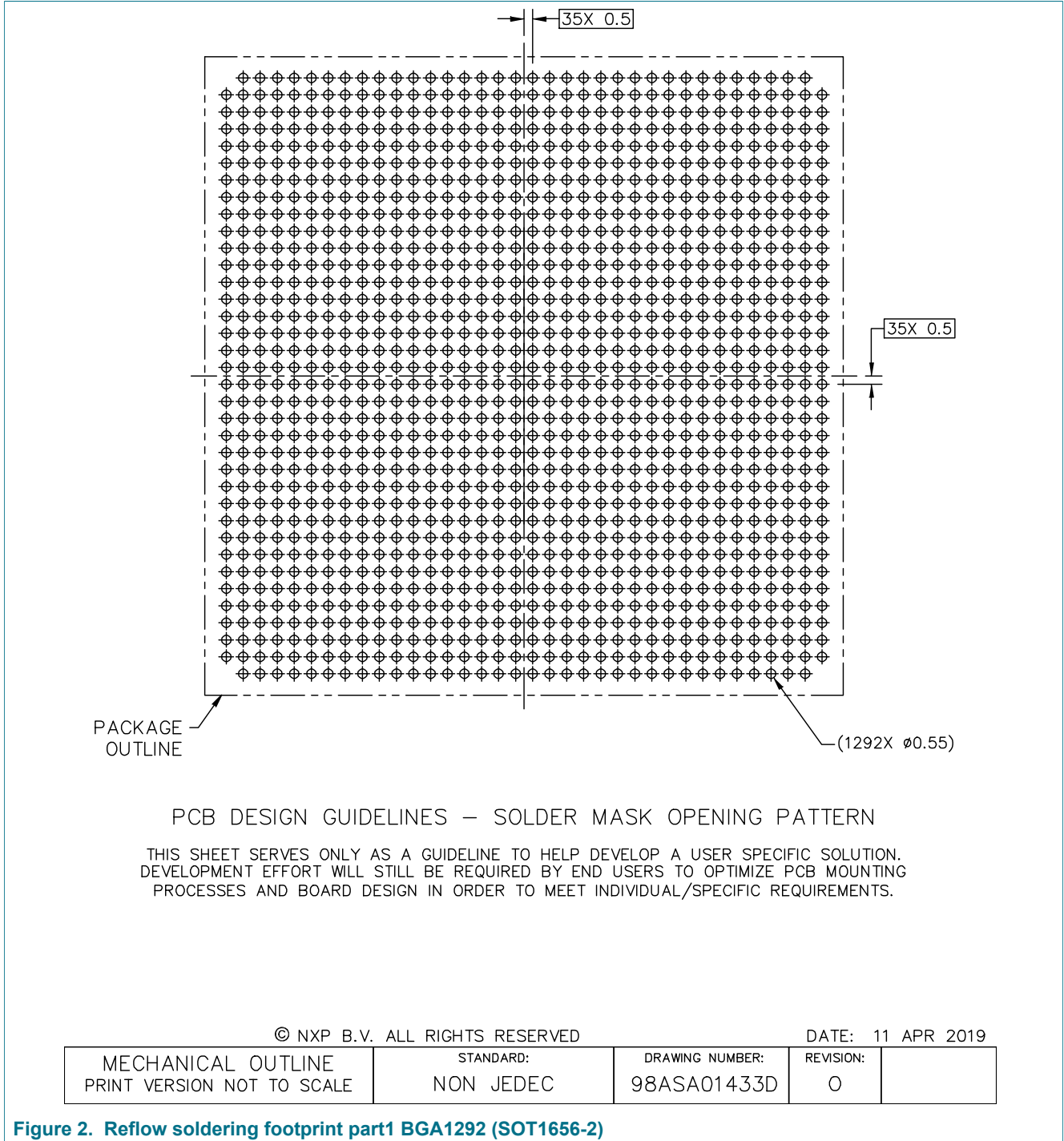


Figure 2. Reflow soldering footprint part1 BGA1292 (SOT1656-2)

BGA1292, plastic, ball grid array; 1292 balls; 1 mm pitch; 37.5 mm x 37.5 mm x 3.17 mm body

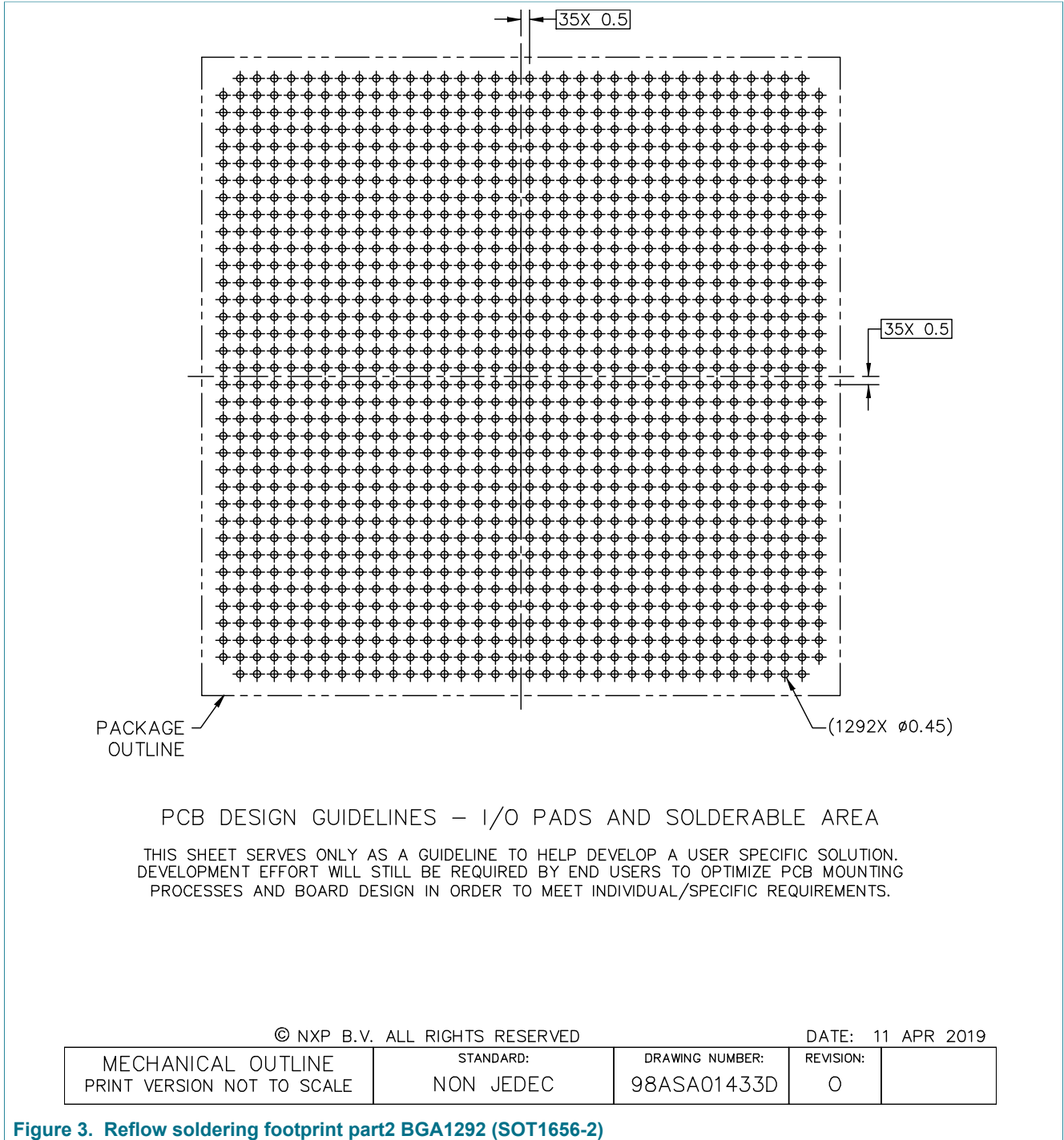


Figure 3. Reflow soldering footprint part2 BGA1292 (SOT1656-2)

BGA1292, plastic, ball grid array; 1292 balls; 1 mm pitch; 37.5 mm x 37.5 mm x 3.17 mm body

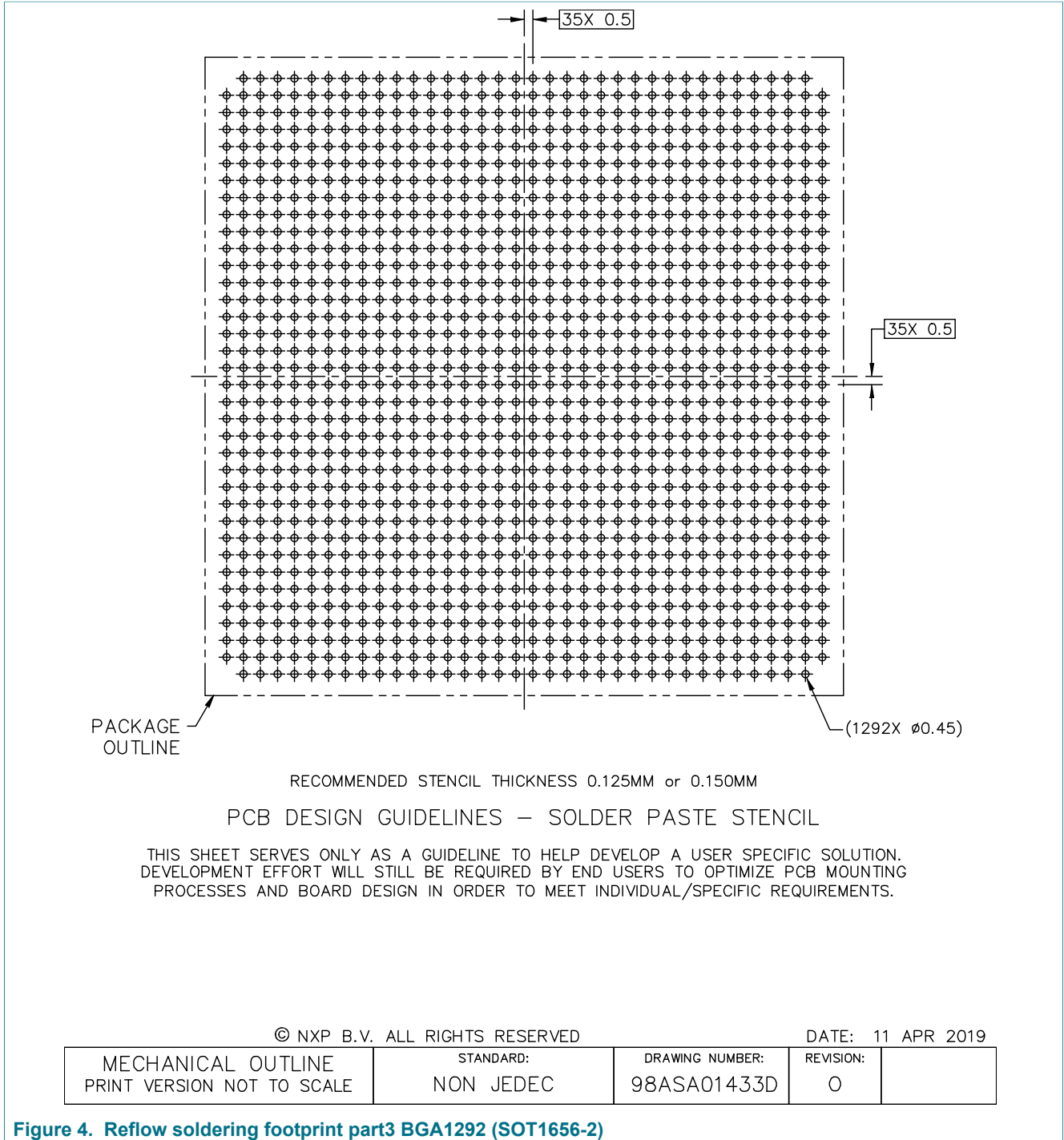


Figure 4. Reflow soldering footprint part3 BGA1292 (SOT1656-2)

BGA1292, plastic, ball grid array; 1292 balls; 1 mm pitch; 37.5 mm x 37.5 mm x 3.17 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
7. LID OVERHANG ON SUBSTRATE NOT ALLOWED.

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DATE: 11 APR 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01433D	REVISION: 0
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Figure 5. Package outline note BGA1292 (SOT1656-2)

4 Legal information

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